Desmear/Electroless Copper for Semi Additive Process

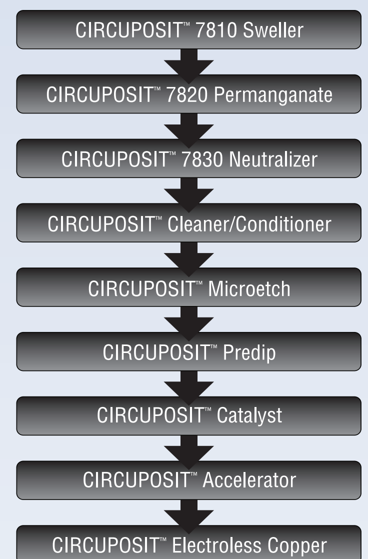
除膠渣及化學沉銅技術應用於半加成製程

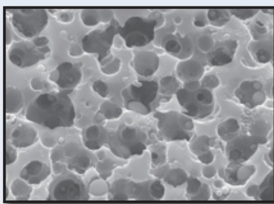
CIRCUPOSIT™ 7800 Electroless Copper

Features and Benefits 特長及優點

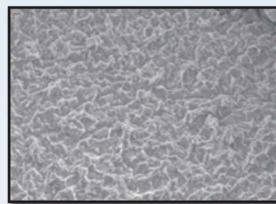
- Uniform and stable adhesion promotion treatment and reliable via bottom cleaning
  能提升均勻且穩定的表面結合能力及對於盲孔孔底有可靠的清潔能力
- Stable and wide process window
  操作範圍大且表現穩定
- High peel strength and optimum surface roughness for insulator adhesion
  抗拉撕強度高，對於絕緣層的貼合表面有最理想的粗糙度
- Excellent plating coverage of electroless copper on insulator and especially on via bottom
  優越的鍍層覆蓋能力，使化學沉銅均勻地覆蓋在絕緣層表面及盲孔底部
- Excellent electrical reliability with high insulation resistance
  在高度的絕緣阻抗下能表現出卓越的信賴性
- Provide great foundation for fine line solution
  為細線路解決方案提供最佳基礎

Process 製程

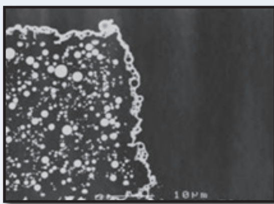


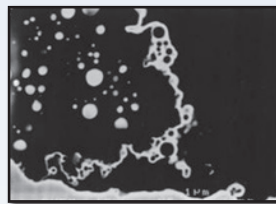


Adhesion promotion on insulator

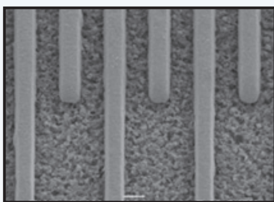


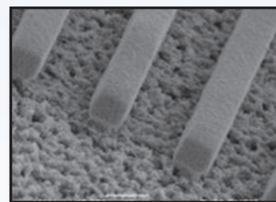
Via bottom cleaning



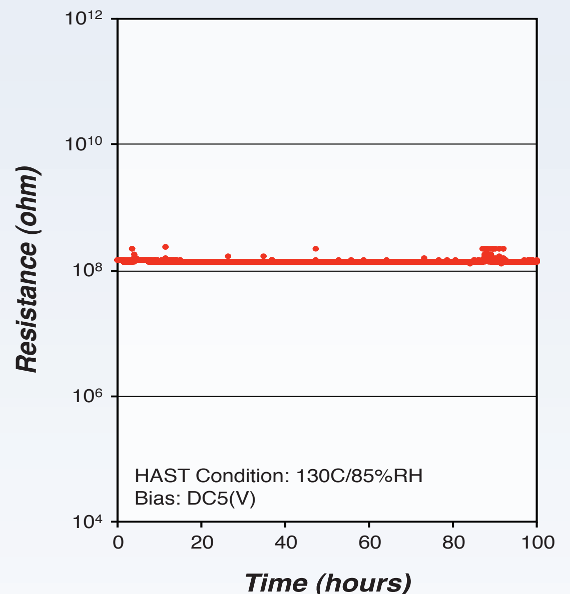


Excellent plating coverage on insulator and via bottom





Fine line capability (L/S = 10/10 μm ultra fine line of ABF GX13)



Excellent reliability performance (by migration test on 10/10 μm)

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